

Appl. No.: 10/089,635
Amdt. dated 02/17/2005
Reply to Office action of December 21, 2004

REMARKS

Reconsideration and allowance of the above identified application is respectfully requested in light of the above amendments and the following remarks.

In the official Action, Claims 25-41 were rejected under §112, first paragraph, as failing to comply with the enablement requirement. Specifically, the Examiner stated that the specification does not disclose what a "partial deformation" is.

The "partial deformation" is explained in the specification of the present application within the paragraph beginning at page 5, line 26, and within the paragraph beginning at page 12, line 13. Particularly, the paragraph on page 12 notes that it is not possible to handle an initial sandwich block of for example 400 dielectric layers and base layers, which have an initial thickness of 0.78m before a rolling process, for example, To overcome this problem, the build up of the base layer is performed step by step followed by a partial deformation or rolling process, to reduce the thickness of already added individual layers prior to adding a further individual layer. During this partial deformation process the thickness of the entire sandwich block will of course also be reduced partially. Not only the base layers are reduced in thickness.

The claims were also rejected under §112, second paragraph, as being indefinite. Claim 25 now clearly recites that the claimed "partial deformation" relates to the build up of at least one of the two base layers of the sandwich block, and this feature is seen to be adequately described in the portions of the specification noted above.

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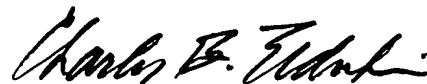
Claims 25-30, 32-34, and 36-38 were rejected as being anticipated by Krauss et al. It is respectfully submitted that the cited Krauss et al. patent does not disclose or suggest the novel features of the present invention as set forth in base Claim 25. Specifically, Krauss et al. teaches the drawing of a stack of layers together with an added carrier plate. According to Figure 9c two packages or stacks of layers can be arranged upon each other for drawing the combined stack together. After drawing the original packages are divided as seen in Figure 9e.

The Krauss et al. patent does not teach or suggest that a plurality of individual layers may be sequentially built up between successive deformation steps for building a base or carrier layer. In other words, there is claimed within the base claim of the present application a repeating adding and deforming process. Such a repeating process is not taught by Krauss et al.

The Examiner's attention is also respectfully directed to Section V of the International Preliminary Examination Report, filed in the present application on April 1, 2003. The IPER is seen to confirm the applicant's position that the prior art does not suggest the claimed invention.

In summary, it is believed that all of the pending claims are in condition for immediate allowance, and such action is solicited.

Respectfully submitted,



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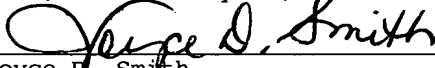
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